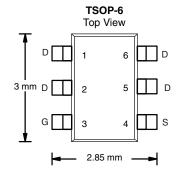




N-Channel 100 V (D-S) MOSFET

MOSFET PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$ Max.	I _D (A) ^a	Q _g (Typ.)		
100	0.126 at V _{GS} = 10 V	3.8			
	0.147 at V _{GS} = 6 V	3.5	2.9 nC		
	0.189 at V _{GS} = 4.5 V	3.1			



Ordering Information: Si3474DV-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- TrenchFET® Power MOSFET
- 100 % R_q and UIS Tested
- Material categorization: For definitions of compliance please see www.vishav.com/doc?99912

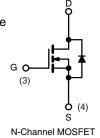


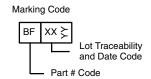
HALOGEN **FREE**

(1, 2, 5, 6)

APPLICATIONS

- DC/DC Converters / Boost Converters
- Load Switch
- LED Backlighting in LCD TVs
- Power Management for Mobile Computing





ABSOLUTE MAXIMUM RATINGS (TA	= 25 °C, unless otl	herwise noted)		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	100	V	
Gate-Source Voltage	V _{GS}	± 20		
	T _C = 25 °C		3.8	
Continuous Drain Commant /T 450 °C\	T _C = 70 °C		3	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	2.8 ^{b, c}	
	T _C = 70 °C		2.3 ^{b, c}	Α
Pulsed Drain Current (t = 100 μs)	I _{DM}	14		
Continuous Source-Drain Diode Current	T _C = 25 °C	l _a	3	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	1.7 ^{b, c}	
Single Pulse Avalanche Current	J 0.1 mlJ	I _{AS}	2.5	
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	0.31	mJ
	T _C = 25 °C		3.6	
Mayimum Daylar Dissination	T _C = 70 °C	D	2.33	w
Maximum Power Dissipation	T _A = 25 °C	P _D	2 ^{b, c}	vv
	T _A = 70 °C		1.3 ^{b, c}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, d}	≤ 5 s	R _{thJA}	50	62.5	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	28	35			

Notes:

- a. Based on T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 110 °C/W.

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MOSFET SPECIFICATIONS	(T _J = 25 °C	, unless otherwise noted)					
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I - 250 uA		59		>//90	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$		- 4.8		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.2		3	٧	
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	l	V _{DS} = 100 V, V _{GS} = 0 V			- 1	μΑ	
Zero Gate voltage Drain Current	IDSS	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			- 10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	5			Α	
		$V_{GS} = 10 \text{ V}, I_D = 2 \text{ A}$		0.102	0.126	6	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 6 V, I _D = 1 A		0.120	0.147	Ω	
	•	$V_{GS} = 4.5 \text{ V}, I_D = 1 \text{ A}$		0.135	0.189		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 20 \text{ V}, I_{D} = 2 \text{ A}$		5		S	
Dynamic ^b							
Input Capacitance	C _{iss}			196		pF	
Output Capacitance	C _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		67			
Reverse Transfer Capacitance	C _{rss}			14			
Total Gate Charge	Q _g Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 2.2 \text{ A}$		5.2	10.4	.4	
Iotal Gate Charge				2.9	5.8	nC	
Gate-Source Charge		V_{DS} = 50 V, V_{GS} = 4.5 V, I_{D} = 2.2 A		1			
Gate-Drain Charge	Q_{gd}			1.4			
Gate Resistance	R_g	f = 1 MHz	0.9	4.3	8.6	Ω	
Turn-On Delay Time	t _{d(on)}			40	60		
Rise Time	t _r	V_{DD} = 50 V, R_L = 27.7 Ω		68	102		
Turn-Off Delay Time	t _{d(off)}	I_D = 1.8 A, V_{GEN} = 4.5 V, R_g = 1 Ω		14	21		
Fall Time	t _f			20	30		
Turn-On Delay Time	t _{d(on)}			8	16	ns	
Rise Time	t _r	$V_{DD} = 50 \text{ V}, R_{L} = 27.7 \Omega$		10	20	- - -	
Turn-Off Delay Time	t _{d(off)}	I_D = 1.8 A, V_{GEN} = 10 V, R_g = 1 Ω		10	20		
Fall Time	t _f			7	14		
Drain-Source Body Diode Characteristi	cs				•	•	
Continuous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$			- 2.1	۸	
Pulse Diode Forward Current (t = 100 μs)	I _{SM}				- 8	A	
Body Diode Voltage	V_{SD}	I _S = 1.8 A		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			23	35	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	$I_F = 1.8 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s},$		21	32	nC	
Reverse Recovery Fall Time	t _a	T _J = 25 °C		17		ns	
Reverse Recovery Rise Time	t _b			6			

Notes:

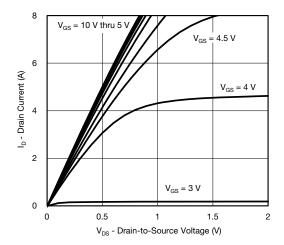
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

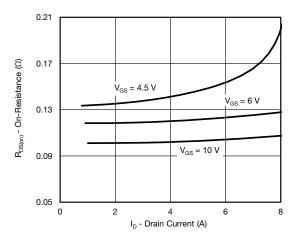
b. Guaranteed by design, not subject to production testing.



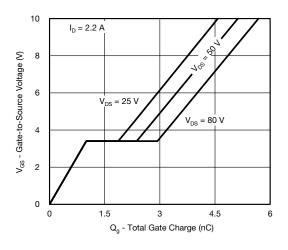
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



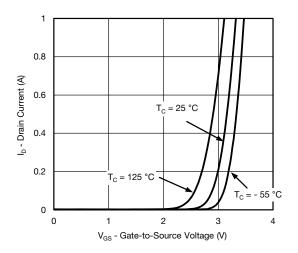
Output Characteristics



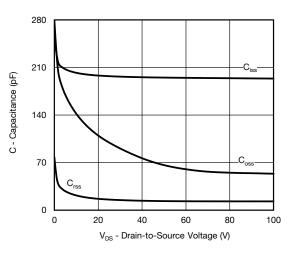
On-Resistance vs. Drain Current and Gate Voltage



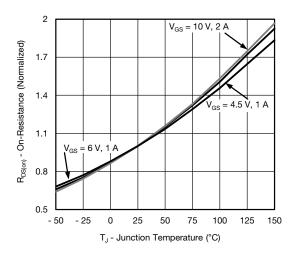
Gate Charge



Transfer Characteristics



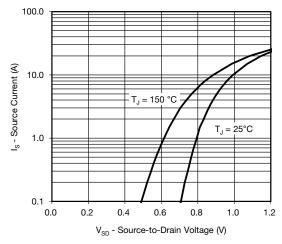
Capacitance

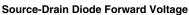


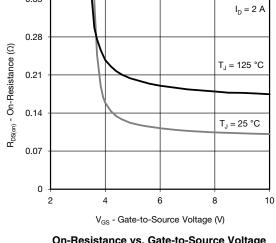
On-Resistance vs. Junction Temperature

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

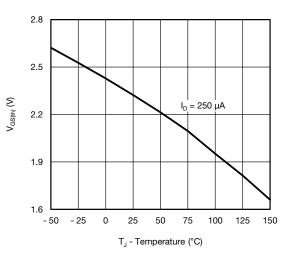




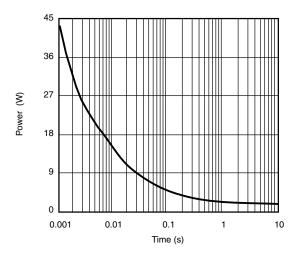


0.35

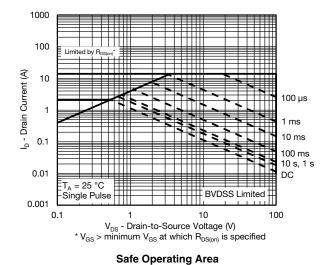
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

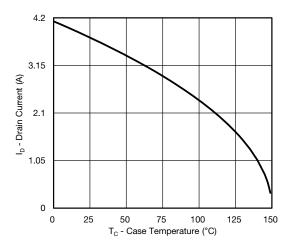


Single Pulse Power

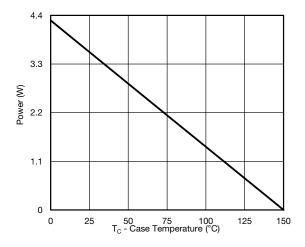


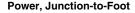


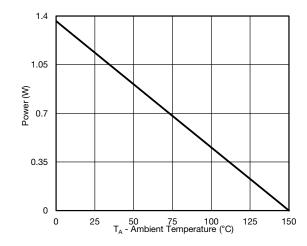
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*







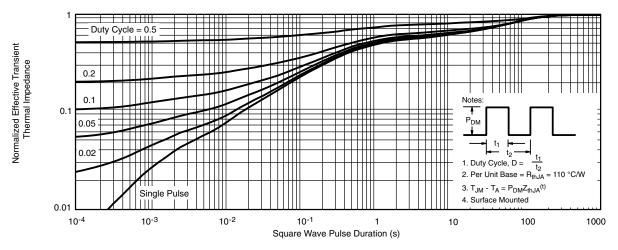
Power, Junction-to-Ambient

 $^{^*}$ The power dissipation P_D is based on $T_{J(max.)}$ = 150 $^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

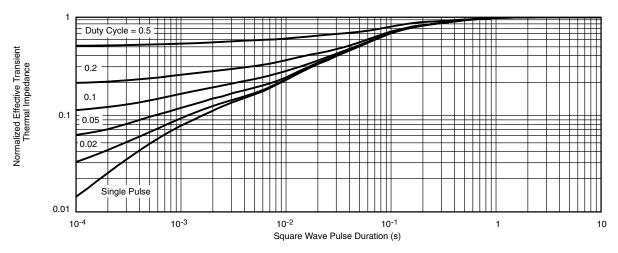
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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TSOP: 5/6-LEAD

JEDEC Part Number: MO-193C





5-LEAD TSOP







	MIL	LIMETER	RS	INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A ₁	0.01	-	0.10	0.0004	-	0.004	
A ₂	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.008		
D	2.95	3.05	3.10	0.116	0.116 0.120		
E	2.70	2.85	2.98	0.106	0.112	0.117	
E ₁	1.55	1.65	1.70	0.061	0.065	0.067	
е	0.95 BSC			0.0374 BSC			
e ₁	1.80	1.90	2.00	0.071	0.079		
L	0.32	-	0.50	0.012	-	0.020	
L ₁	0.60 Ref			0.024 Ref			
L ₂	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
θ1		7° Nom		7° Nom			
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							

Document Number: 71200 18-Dec-06



Recommended Land Pattern For TSOP-5L / TSOP-6L



Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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